

# NBXDPA019

## 2.5 V / 3.3 V, 125 MHz / 250 MHz LVDS Clock Oscillator

The NBXDPA019 dual frequency crystal oscillator (XO) is designed to meet today's requirements for 2.5 V and 3.3 V LVDS clock generation applications. The device uses a high Q fundamental crystal and Phase Lock Loop (PLL) multiplier to provide selectable 125 MHz or 250 MHz, ultra low jitter and phase noise LVDS differential output.

This device is a member of ON Semiconductor's PureEdge™ clock family that provides accurate and precision clock solutions.

Available in 5 mm x 7 mm SMD (CLCC) package on 16 mm tape and reel in quantities of 1000.

### Features

- LVDS Differential Output
- Uses High Q Fundamental Mode Crystal and PLL Multiplier
- Ultra Low Jitter and Phase Noise – 0.5 ps (12 kHz – 20 MHz)
- Selectable Output Frequency – 125 MHz (default) / 250 MHz
- Hermetically Sealed Ceramic SMD Package
- RoHS Compliant
- Operating Range: 2.5 V  $\pm 5\%$   
3.3 V  $\pm 10\%$
- Total Frequency Stability –  $\pm 50$  ppm
- This is a Pb-Free Device

### Applications

- Ethernet, Gigabit Ethernet
- Infiniband
- Base Stations

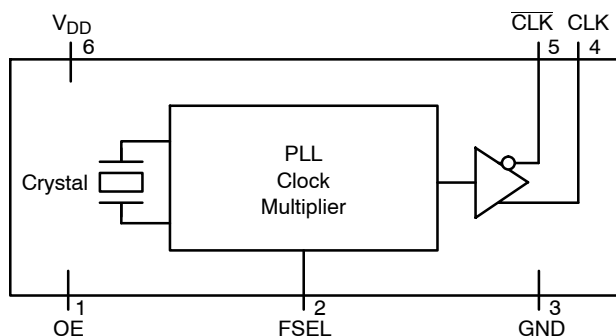
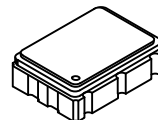


Figure 1. Simplified Logic Diagram



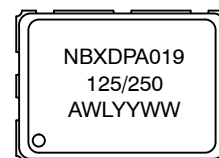
**ON Semiconductor®**

<http://onsemi.com>



**6 PIN CLCC  
LN SUFFIX  
CASE 848AB**

### MARKING DIAGRAM



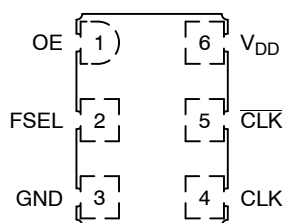
NBXDPA019 = NBXDPA019 ( $\pm 50$  PPM)  
125/250 = Output Frequency (MHz)  
A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week  
G or ■ = Pb-Free Package

### ORDERING INFORMATION

Device	Package	Shipping†
NBXDPA019LN1TAG	CLCC-6 (Pb-Free)	1000/ Tape & Reel
NBXDPA019LNHTAG	CLCC-6 (Pb-Free)	100/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# NBXDPA019



**Figure 2. Pin Connections** (Top View)

**Table 1. PIN DESCRIPTION**

Pin No.	Symbol	I/O	Description
1	OE	LVTTL/LVCMOS Control Input	Output Enable Pin. When left floating pin defaults to logic HIGH and output is active. See OE pin description Table 2.
2	FSEL	LVTTL/LVCMOS Control Input	Output Frequency Select Pin. Pin will default to logic HIGH when left open. See Output Frequency Select pin description Table 3.
3	GND	Power Supply	Ground 0 V
4	CLK	LVDS Output	Non-Inverted Clock Output. Typically loaded with 100 $\Omega$ receiver termination resistor across differential pair.
5	$\overline{\text{CLK}}$	LVDS Output	Inverted Clock Output. Typically loaded with 100 $\Omega$ receiver termination resistor across differential pair.
6	V <sub>DD</sub>	Power Supply	Positive power supply voltage. Voltage should not exceed 2.5 V $\pm$ 5% or 3.3 V $\pm$ 10%.

**Table 2. OUTPUT ENABLE TRI-STATE FUNCTION**

OE Pin	Output Pins
Open	Active
HIGH Level	Active
LOW Level	High Z

**Table 3. OUTPUT FREQUENCY SELECT**

FSEL Pin	Output Frequency (MHz)
Open (pin will float high)	125
HIGH Level	125
LOW Level	250

**Table 4. ATTRIBUTES**

Characteristic	Value
Input Default State Resistor	170 k $\Omega$
ESD Protection Human Body Model Machine Model	2 kV 200 V
Meets or Exceeds JEDEC Standard EIA/JESD78 IC Latchup Test	

1. For additional Moisture Sensitivity information, refer to Application Note AND8003/D.

**Table 5. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V <sub>DD</sub>	Positive Power Supply	GND = 0 V		4.6	V
I <sub>out</sub>	LVDS Output Current	Continuous Surge		25 50	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-55 to +120	°C
T <sub>sol</sub>	Wave Solder	See Figure 6		260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

**Table 6. DC CHARACTERISTICS** ( $V_{DD} = 2.5\text{ V} \pm 5\%$  or  $V_{DD} = 3.3\text{ V} \pm 10\%$ ,  $GND = 0\text{ V}$ ,  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ) (Note 2)

Symbol	Characteristic	Conditions	Min.	Typ.	Max.	Units
$I_{DD}$	Power Supply Current			78	105	mA
$V_{IH}$	OE and FSEL Input HIGH Voltage		2000		$V_{DD}$	mV
$V_{IL}$	OE and FSEL Input LOW Voltage		$GND - 300$		800	mV
$I_{IH}$	Input HIGH Current	OE FSEL	-100 -100		+100 +100	$\mu\text{A}$
$I_{IL}$	Input LOW Current	OE FSEL	-100 -100		+100 +100	$\mu\text{A}$
$\Delta V_{OD}$	Change in Magnitude of $V_{OD}$ for Complementary Output States (Note 3)		0	1	25	mV
$V_{OS}$	Offset Voltage		1125		1375	mV
$\Delta V_{OS}$	Change in Magnitude of $V_{OS}$ for Complementary Output States (Note 3)		0	1	25	mV
$V_{OH}$	Output HIGH Voltage	$V_{DD} = 2.5\text{ V}$ $V_{DD} = 3.3\text{ V}$		1425	1600	mV
$V_{OL}$	Output LOW Voltage	$V_{DD} = 2.5\text{ V}$ $V_{DD} = 3.3\text{ V}$	900	1075		mV
$V_{OD}$	Differential Output Voltage		250		450	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- Measurement taken with outputs terminated with 100 ohm across differential pair. See Figure 5.
- Parameter guaranteed by design verification not tested in production.

# NBXDPA019

**Table 7. AC CHARACTERISTICS** ( $V_{DD} = 2.5\text{ V} \pm 5\%$  or  $V_{DD} = 3.3\text{ V} \pm 10\%$ ,  $GND = 0\text{ V}$ ,  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ) (Note 4)

Symbol	Characteristic	Conditions	Min.	Typ.	Max.	Units
$f_{CLKOUT}$	Output Clock Frequency	FSEL = HIGH		125		MHz
		FSEL = LOW		250		
$\Delta f$	Frequency Stability – NBXDPA019	(Note 5)			$\pm 50$	ppm
$\Phi_{NOISE}$	Phase-Noise Performance $f_{CLKout} = 125\text{ MHz}/250\text{ MHz}$ (See Figures 3 and 4)	100 Hz of Carrier		-108/-103		dBc/Hz
		1 kHz of Carrier		-122/-116		dBc/Hz
		10 kHz of Carrier		-129/-123		dBc/Hz
		100 kHz of Carrier		-129/-124		dBc/Hz
		1 MHz of Carrier		-136/-131		dBc/Hz
		10 MHz of Carrier		-159/-156		dBc/Hz
$t_{jit}(\Phi)$	RMS Phase Jitter	12 kHz to 20 MHz		0.5	0.75	ps
$t_{jitter}$	Cycle to Cycle, RMS	1000 Cycles		4	8	ps
	Cycle to Cycle, Peak-to-Peak	1000 Cycles		17	35	ps
	Period, RMS	10,000 Cycles		2	4	ps
	Period, Peak-to-Peak	10,000 Cycles		7	20	ps
$t_{OE/OD}$	Output Enable/Disable Time				200	ns
$t_{DUTY\_CYCLE}$	Output Clock Duty Cycle (Measured at Cross Point)		48	50	52	%
$t_R$	Output Rise Time (20% and 80%)			250	400	ps
$t_F$	Output Fall Time (80% and 20%)			250	400	ps
$t_{start}$	Start-up Time			1	5	ms
	Aging	1 <sup>st</sup> Year			3	ppm
		Every Year After 1 <sup>st</sup>			1	ppm

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

4. Measurement taken with outputs terminated with 100 ohm across differential pair. See Figure 5.
5. Parameter guarantees 10 years of aging. Includes initial stability at 25°C, shock, vibration and first year aging.

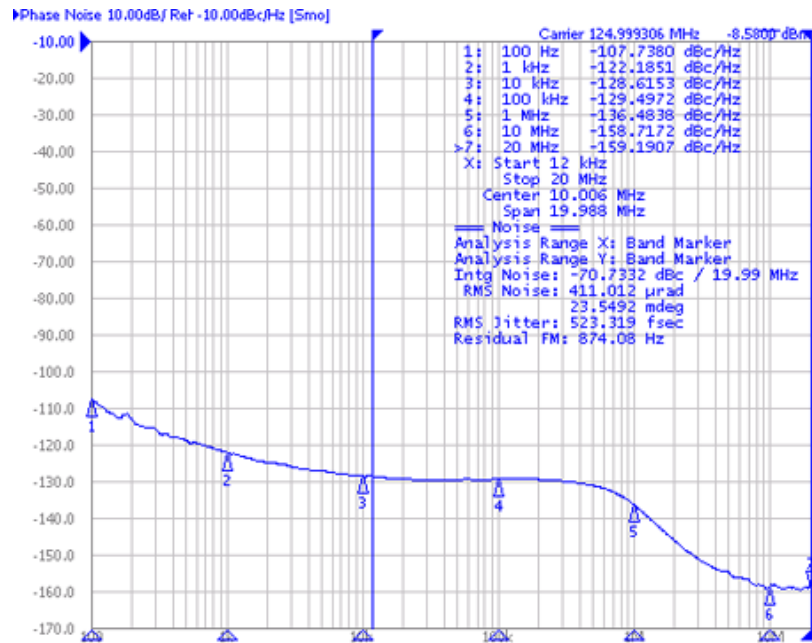


Figure 3. Typical Phase Noise Plot at 125 MHz

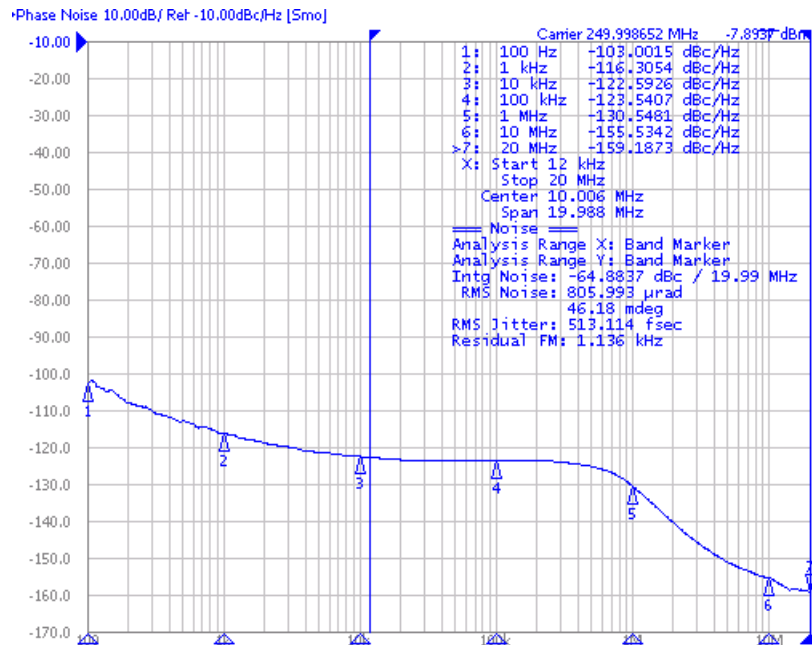


Figure 4. Typical Phase Noise Plot at 250 MHz

Table 8. RELIABILITY COMPLIANCE

Parameter	Standard	Method
Shock	Mechanical	MIL-STD-833, Method 2002, Condition B
Solderability	Mechanical	MIL-STD-833, Method 2003
Vibration	Mechanical	MIL-STD-833, Method 2007, Condition A
Solvent Resistance	Mechanical	MIL-STD-202, Method 215
Resistance to Soldering Heat	Mechanical	MIL-STD-203, Method 210, Condition I or J
Thermal Shock	Environment	MIL-STD-833, Method 1001, Condition A
Moisture Resistance	Environment	MIL-STD-833, Method 1004

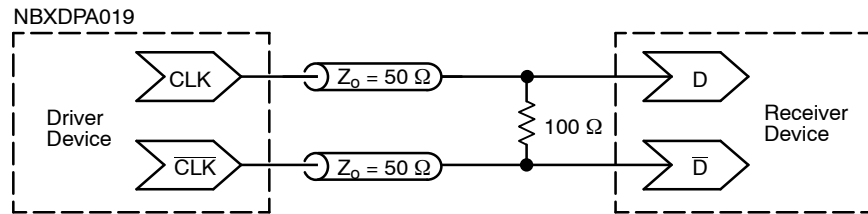


Figure 5. Typical Termination for Output Driver and Device Evaluation

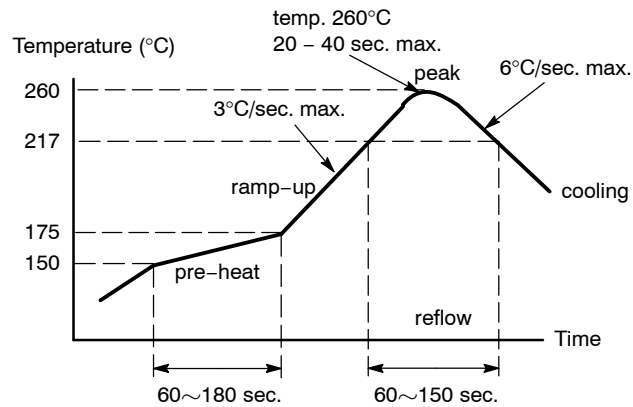
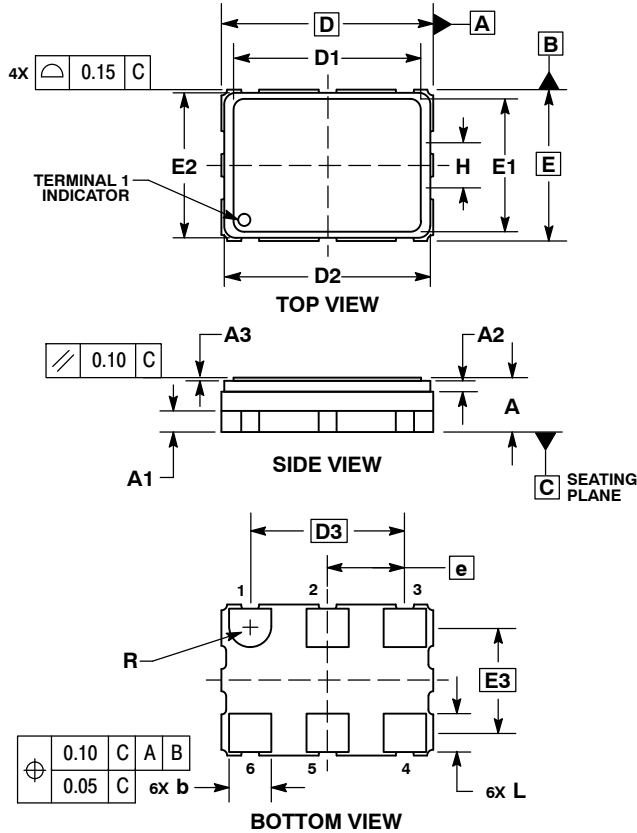


Figure 6. Recommended Reflow Soldering Profile

# NBXDPA019

## PACKAGE DIMENSIONS

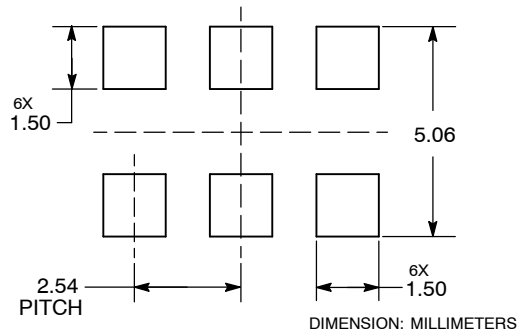
6 PIN CLCC, 7x5, 2.54P  
CASE 848AB-01  
ISSUE C



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.


DIM	MIN	NOM	MAX
A	1.70	1.80	1.90
A1		0.70 REF	
A2		0.36 REF	
A3	0.08	0.10	0.12
b	1.30	1.40	1.50
D		7.00 BSC	
D1	6.17	6.20	6.23
D2	6.66	6.81	6.96
D3		5.08 BSC	
E		5.00 BSC	
E1	4.37	4.40	4.43
E2	4.65	4.80	4.95
E3		3.49 BSC	
e		2.54 BSC	
H		1.80 REF	
L	1.17	1.27	1.37
R		0.70 REF	

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PureEdge is a trademark of Semiconductor Components Industries, LLC (SCILLC).

ON Semiconductor and  are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

### PUBLICATION ORDERING INFORMATION

**LITERATURE FULFILLMENT:**  
Literature Distribution Center for ON Semiconductor  
P.O. Box 5163, Denver, Colorado 80217 USA  
**Phone:** 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
**Email:** orderlit@onsemi.com

**N. American Technical Support:** 800-282-9855 Toll Free  
USA/Canada  
**Europe, Middle East and Africa Technical Support:**  
Phone: 421 33 790 2910  
**Japan Customer Focus Center**  
Phone: 81-3-5773-3850

**ON Semiconductor Website:** [www.onsemi.com](http://www.onsemi.com)  
**Order Literature:** <http://www.onsemi.com/orderlit>  
For additional information, please contact your local Sales Representative

NBXDPA019/D